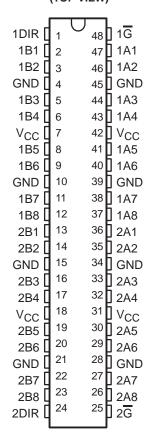
SCAS097B - DECEMBER 1989 - REVISED APRIL 1996

- Members of the Texas Instruments
  Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines Directly
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V<sub>CC</sub> and GND Configuration to Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings, Thin Shrink Small-Outline (DGG) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

### description

The SN54ACT16245 and 74ACT16245 are 16-bit bus transceivers organized as dual-octal noninverting 3-state transceivers and designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

SN54ACT16245 . . . WD PACKAGE 74ACT16245 . . . DGG OR DL PACKAGE (TOP VIEW)



The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The enable  $(\overline{G})$  input can be used to disable the devices so that the buses are effectively isolated.

The SN54ACT16245 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16245 is characterized for operation from –40°C to 85°C.

#### **FUNCTION TABLE**

	TROL UTS	OPERATION
G	DIR	
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

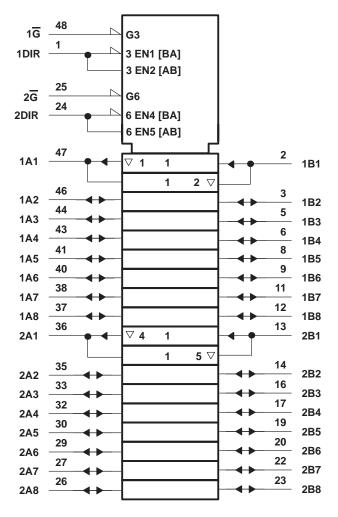


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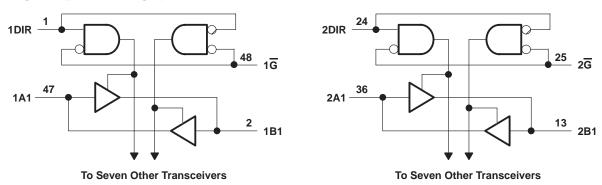


## logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# logic diagram (positive logic)





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (see Note 1)	
Output voltage range, V <sub>O</sub> (see Note 1)	0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	
Continuous current through V <sub>CC</sub> or GND	±400 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note	2): DGG package 0.85 W
, , , , , , , , , , , , , , , , , , ,	DL package
Storage temperature range, T <sub>sta</sub>	. •

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

		SN54AC	Γ16245	74ACT	16245	UNIT
		MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage (see Note 4)	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
VIL	Low-level input voltage		0.8		0.8	V
٧ <sub>I</sub>	Input voltage	0	VCC	0	VCC	V
Vo	Output voltage	0	VCC	0	VCC	V
loh	High-level output current		-24		-24	mA
loL	Low-level output current		24		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	0	10	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTES: 3. Unused inputs should be tied to V<sub>CC</sub> through a pullup resistor of approximately 5 kΩ or greater to keep them from floating.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

<sup>4.</sup> All V<sub>CC</sub> and GND pins must be connected to the proper voltage power supply.

# SN54ACT16245, 74ACT16245 **16-BIT BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

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### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	RAMETER	TEST CONDITIONS	V	T,	λ = 25°C	;	SN54AC	Γ16245	74ACT	16245	UNIT	
TANAMETER		TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONT	
		I <sub>OH</sub> = -50 μA	4.5 V	4.4			4.4		4.4			
		ΙΟΗ = -30 μΑ	5.5 V	5.4			5.4		5.4			
V/011		I <sub>OH</sub> = -24 mA	4.5 V	3.94			3.94		3.8		V	
VOH		10H = -24 IIIA	5.5 V	4.94			4.94		4.8		V	
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85					
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85			
		I <sub>OL</sub> = 50 μA	4.5 V			0.1		0.1		0.1		
		ΙΟΓ = 30 μΑ	5.5 V			0.1		0.1		0.1		
\/o:		I <sub>OL</sub> = 24 mA	4.5 V			0.36		0.5		0.44	V	
VOL		IOL = 24 IIIA	5.5 V			0.36		0.5		0.44	·	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V					1.65				
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V							1.65		
Ц	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ	
loz	A or B ports <sup>‡</sup>	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μΑ	
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		160		80	μΑ	
ΔlCC§		One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V			0.9		1		1	mA	
Ci	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4.5						pF	
C <sub>io</sub>	A or B ports	$V_O = V_{CC}$ or GND	5 V		16						pF	

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

### switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	գ = 25°C	;	SN54AC1	Γ16245	74ACT	UNIT	
TANAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONIT
<sup>t</sup> PLH	A or B	B or A	3.2	6.9	9.3	3.2	11.5	3.2	10.5	ns I
<sup>t</sup> PHL	AOIB	BULA	2.6	6.4	9.2	2.6	11.1	2.6	10.2	
<sup>t</sup> PZH	G	B or A	2.7	6.4	9.1	2.7	10.9	2.7	10	
<sup>t</sup> PZL	G		3.4	7.4	10.5	3.4	12.6	3.4	11.6	ns
<sup>t</sup> PHZ	G	B or A	5.8	9.2	11.6	5.8	13.4	5.8	12.6	20
<sup>t</sup> PLZ	G	B OF A	5.5	8.5	10.8	5.5	12.7	5.5	11.8	ns

# operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

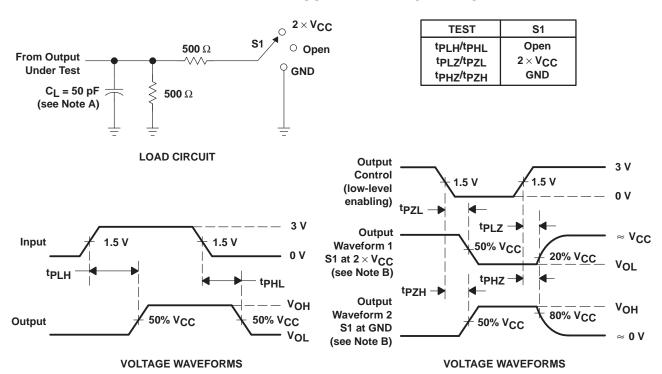
	PARAMETER	TEST COI	TEST CONDITIONS			
C . Power dissination conseitance per transceiver	Outputs enabled	C <sub>1</sub> = 50 pF,	f = 1 MHz	52	рF	
Cpd	Power dissipation capacitance per transceiver	Outputs disabled	CL = 50 pr,	I = I IVITIZ	10	pΓ



<sup>‡</sup> For I/O ports, the parameter IOZ includes the input leakage current I<sub>I</sub>.

<sup>§</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9202301MXA	ACTIVE	CFP	WD	48	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	5962-9202301MX A SNJ54ACT16245W D	Samples
74ACT16245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245	Samples
74ACT16245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245	Samples
74ACT16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245	Samples
74ACT16245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245	Samples
74ACT16245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245	Samples
74ACT16245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16245	Samples
SNJ54ACT16245WD	ACTIVE	CFP	WD	48	1	TBD	SNPB	N / A for Pkg Type		5962-9202301MX A SNJ54ACT16245W D	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".



## PACKAGE OPTION ADDENDUM

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- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
74ACT16245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

Device	Pevice Package Type Package Drawing				Length (mm)	Width (mm)	Height (mm)
74ACT16245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
74ACT16245DLR	SSOP	DL	48	1000	367.0	367.0	55.0

### WD (R-GDFP-F\*\*)

#### **CERAMIC DUAL FLATPACK**

### **48 LEADS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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